



Call for Contributed Articles and Papers for the Feature Topic of “Large-Area and Flexible Electronics” in IEEE Electron Devices Magazine (ED-M), Vol. 2, No. 1 (March 2024).

The IEEE Electron Devices Magazine invites manuscript submissions within the scope of Large Area Electronics and Flexible Electronics. The IEEE Electron Devices Magazine focuses on the publication of peer-reviewed tutorial and survey papers related to the wider field of electron devices and its application. The purpose of this special issue is to document the latest frontiers in fundamental research and technological development in the fields of large-area electronics and flexible electronics devices.

The primary focus is on large-area and flexible device technologies, and application areas of interest include but are not limited to:

- Displays, active and passive matrix backplanes, backlights
- Sensors, Actuators
- Photovoltaics, energy harvesting, batteries
- Antennas, RFID
- Lighting
- Wearable devices

Along with focusing on device design, fabrication processes, and performance; additional aspects interesting to discuss include: modeling, materials, packaging/metallization, system-level integration, and additive manufacturing.

Submission instructions:

Manuscripts up to 8 pages should be submitted in a double column format using an IEEE style file. Please visit the following link to download the templates:

[IEEE Article Templates - IEEE Author Center Journals](#)

Additional information IEEE Electron Devices Magazine can be found at:

[IEEE Electron Devices Magazine - IEEE Electron Devices Society](#)

All submissions will be reviewed in accordance with the normal procedures of Electron Devices Magazine.

Submissions of open columns (1 page) will also be considered.

Space in each ED-M issue is limited. Therefore, papers passing the peer review successfully may be ranked and be accepted for publication in the order of ranking.

Submission deadline: September 15, 2023

Publication date: March 2024

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